IPC ASSOCIATION CONTELECTRONICS INDU	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier Inf	formation	,							,					
ompany name	ne*	Company unique ID			τ	Unique ID Authority				Response Date*				
onsemi											2024-05-20			
Contact Name	:	Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized Rep	epresentative*	Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-Env-S	Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
Reg	quester Item Number	Mfr Item	Number Mfr Item Name				Effective Date Version Manufacturi		Manufacturing Site	W	eight*	UOM	Unit Type	
	2SK4177-DL-1E NCH 2A 1500V 1		NCH 2A 1500V 13	ohms TO263-2	L	2024-05-20	20 KR8		14	185.2	mg	Each		
Ianufactur	ring Proccess Informa	ation											·	
Tern	Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 M			STD-020 MSL	Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles						eles			
Matte Tin (Sn) - annealed			CU Alloy 1			245 C 30		30	second	s <b>3</b>				
omments														
vel 1 - maxim	num time at peak temperat	ure during sol	dering is 10-	30 seconds										
or more infor	rmation regarding materia	l composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to suc										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	12.3	mg	Supplier	Silicon (Si)	7440-21-3		12.3	mg
Die Attach	22.45	mg	Supplier	Silver (Ag)	7440-22-4		0.3368	mg
			A	Lead (Pb)	7439-92-1	7a	20.9908	mg
			Supplier	Tin (Sn)	7440-31-5		1.1225	mg
Lead Frame	834.15	mg	В	Nickel (Ni)	7440-02-0		0.5839	mg
			Supplier	Iron (Fe)	7439-89-6		0.8342	mg
			Supplier	Copper (Cu)	7440-50-8		832.4818	mg
			Supplier	Phosphorus (P)	7723-14-0		0.2502	mg
Mold Compound-Black	609.51	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		18.2853	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		121.902	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		15.2378	mg
			Supplier	Carbon Black (C)	1333-86-4		6.0951	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		447.9899	mg
Plating	3.7	mg	Supplier	Tin (Sn)	7440-31-5		3.7	mg
Wire Bond - Al	3.09	mg	Supplier	Aluminum (Al)	7429-90-5		3.09	mg